

1010/062171 pro

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1017 U.S. Pro  
10/082174

**U.S. UTILITY Patent Application**

**PATENT NUMBER and  
ISSUE DATE**

APPL NUM	FILING DATE	CLASS	SUBCLASS	GAU	EXAMINER
10082174	02/26/2002	257	166	281	WT 2004

**\*\*APPLICANTS:** Crane Stanford; Alcancia Vicente; Jeon Myoung-Soo

\*\*CONTINUING DATA VERIFIED:

10

\*\* FOREIGN APPLICATIONS VERIFIED:

11

PG-PUB	DO NOT PUBLISH	RESCIND	
Foreign priority claimed 35 USC 119 conditions met		<input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> yes <input checked="" type="checkbox"/> no	ATTORNEY DOCKET NO 040879-5092
Verified and Acknowledged Examiners initials			

TITLE : Microstrip relay semiconductor die package

NOTICE OF ALLOWANCE MAILED		Assistant Examiner	CLAIMS ALLOWED		
			Total Claims	Print Claim for O.G.	
ISSUE FEE			DRAWING		
Amount Due	Date Paid		Sheets Drwg.	Figs. Drwg.	Print Fig.

2 MIN.

## DISCLAIMER

PREPARED FOR ISSUE

### Application Exercise

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